

## TO-252 Pin Configuration

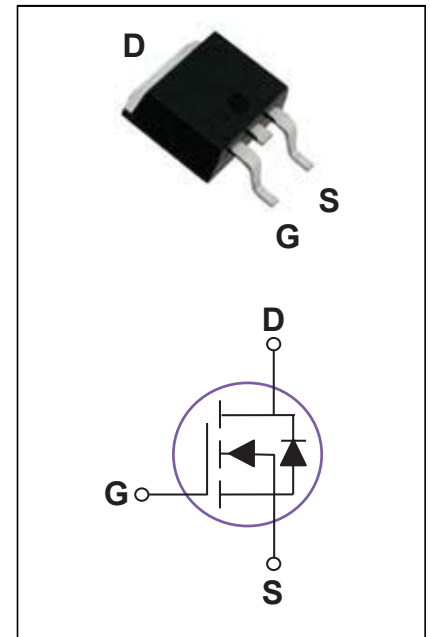
BVDSS	R <sub>DS(ON)</sub>	I <sub>D</sub>
30V	6mΩ	80A

**FEATURES**

- 30V, 80A, R<sub>DS(ON)</sub> = 6mΩ @ V<sub>GS</sub> = 10V
- Improved dv/dt capability
- Fast switching
- 100% EAS Guaranteed
- Green Device Available

**APPLICATIONS**

- MB / VGA / Vcore
- POL Applications
- SMPS 2<sup>nd</sup> SR



## MAXIMUM RATINGS AND CHARACTERISTICS

@ 25°C Ambient Temperature (unless otherwise noted)

Parameter	Symbol	Rating	Units
Drain-Source Voltage	V <sub>DS</sub>	30	V
Gate-Source Voltage	V <sub>GS</sub>	±20	V
Drain Current – Continuous (T <sub>C</sub> =25°C)	I <sub>D</sub>	80	A
Drain Current – Continuous (T <sub>C</sub> =100°C)		51	A
Drain Current – Pulsed <sup>1</sup>	I <sub>DM</sub>	320	A
Single Pulse Avalanche Energy <sup>2</sup>	EAS	88	mJ
Single Pulse Avalanche Current <sup>2</sup>	I <sub>AS</sub>	42	A
Power Dissipation (T <sub>C</sub> =25°C)	P <sub>D</sub>	54	W
Power Dissipation – Derate above 25°C		0.43	W/°C
Storage Temperature Range	T <sub>STG</sub>	-55 to +150	°C
Operating Junction Temperature Range	T <sub>J</sub>	-55 to +150	°C

### Thermal Characteristics

Parameter	Symbol	Typ	Max	Unit
Thermal Resistance Junction to ambient	R <sub>θJA</sub>	---	62	°C/W
Thermal Resistance Junction to Case	R <sub>θJC</sub>	---	2.3	°C/W

## MOSFET ELECTRICAL CHARACTERISTICS $T_A=25^\circ\text{C}$ unless otherwise specified

### Off Characteristics

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS}=0V, I_D=250\mu A$	30	---	---	V
$BV_{DSS}$ Temperature Coefficient	$\Delta BV_{DSS}/\Delta T_J$	Reference to $25^\circ\text{C}, I_D=1\text{mA}$	---	0.04	---	
Drain-Source Leakage Current	$I_{DSS}$	$V_{DS}=30V, V_{GS}=0V, T_J=25^\circ\text{C}$	---	---	1	$\mu A$
		$V_{DS}=24V, V_{GS}=0V, T_J=125^\circ\text{C}$	---	---	10	$\mu A$
Gate-Source Leakage Current	$I_{GSS}$	$V_{GS}=\pm 20V, V_{DS}=0V$	---	---	$\pm 100$	nA
Static Drain-Source On-Resistance <sup>3</sup>	$R_{DS(ON)}$	$V_{GS}=10V, I_D=20A$	---	4.8	6	$m\Omega$
		$V_{GS}=4.5V, I_D=10A$	---	6.5	9	$m\Omega$
Gate Threshold Voltage	$V_{GS(th)}$	$V_{GS}=V_{DS}, I_D=250\mu A$	1	1.6	2.5	V
$V_{GS(th)}$ Temperature Coefficient	$\Delta V_{GS(th)}$		---	-4	---	$mV/^\circ\text{C}$
Forward Transconductance	$g_{fs}$	$V_{DS}=10V, I_D=10A$	---	18	---	S

### Dynamic Characteristics

Total Gate Charge <sup>3,4</sup>	$Q_g$	$V_{DS}=15V, V_{GS}=4.5V, I_D=20A$	---	11.1	---	nC
Gate-Source Charge <sup>3,4</sup>	$Q_{gs}$		---	1.85	---	
Gate-Drain Charge <sup>3,4</sup>	$Q_{gd}$		---	6.8	---	
Turn-On Delay Time <sup>3,4</sup>	$T_{d(on)}$	$V_{DD}=15V, V_{GS}=10V, R_G=3.3\Omega, I_D=15A$	---	7.5	---	ns
Rise Time <sup>3,4</sup>	$T_r$		---	14.5	---	
Turn-Off Delay Time <sup>3,4</sup>	$T_{d(off)}$		---	35.2	---	
Fall Time <sup>3,4</sup>	$T_f$		---	9.6	---	
Input Capacitance	$C_{iss}$	$V_{DS}=25V, V_{GS}=0V, F=1\text{MHz}$	---	1160	---	pF
Output Capacitance	$C_{oss}$		---	200	---	
Reverse Transfer Capacitance	$C_{rss}$		---	180	---	
Gate resistance	$R_g$	$V_{GS}=0V, V_{DS}=0V, F=1\text{MHz}$	---	2.5	---	$\Omega$

### Guaranteed Avalanche Energy

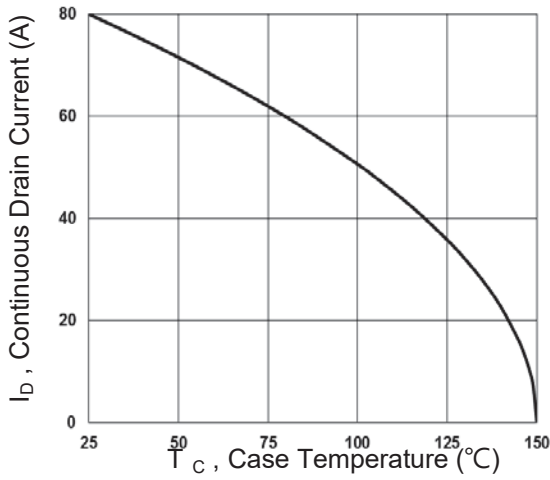
Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Single Pulse Avalanche Energy	EAS	$V_{DD}=25V, L=0.1\text{mH}, I_{AS}=20A$	20	---	---	mJ

### Drain-Source Diode Characteristics

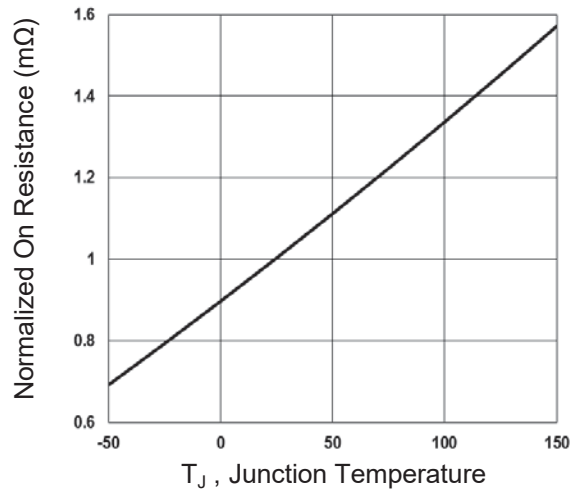
Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Continuous Source Current	$I_S$	$V_G=V_D=0V, \text{Force Current}$	---	---	80	A
Pulsed Source Current <sup>3</sup>	$I_{SM}$		---	---	320	A
Diode Forward Voltage <sup>3</sup>	$V_{SD}$	$V_{GS}=0V, I_S=1A, T_J=25^\circ\text{C}$	---	---	1	V
Reverse Recovery Time	$t_{rr}$	$V_{GS}=0V, I_S=1A, di/dt=100A/\mu s$ $T_J=25^\circ\text{C}$	---	---	---	ns
Reverse Recovery Charge	$Q_{rr}$		---	---	---	nC

Note :

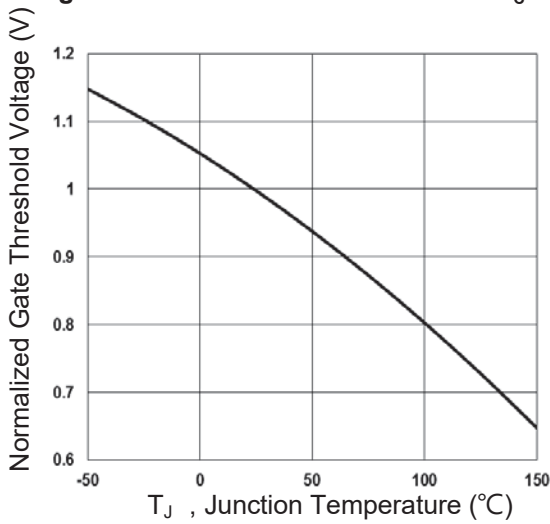
1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2.  $V_{DD}=25V, V_{GS}=10V, L=0.1\text{mH}, I_{AS}=42A, R_G=25\Omega, \text{Starting } T_J=25^\circ\text{C}$ .
3. The data tested by pulsed, pulse width  $\leq 300\mu s$ , duty cycle  $\leq 2\%$ .
4. Essentially independent of operating temperature.



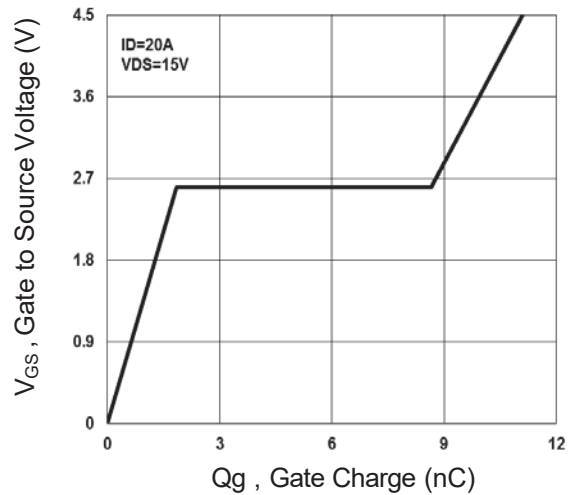
**Fig.1 Continuous Drain Current vs.  $T_c$**



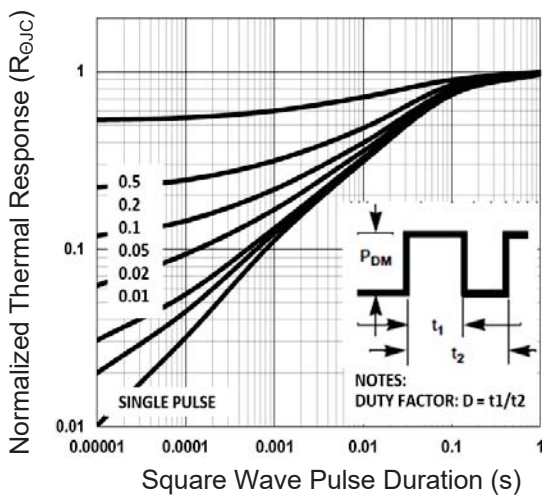
**Fig.2 Normalized RDSON vs.  $T_j$**



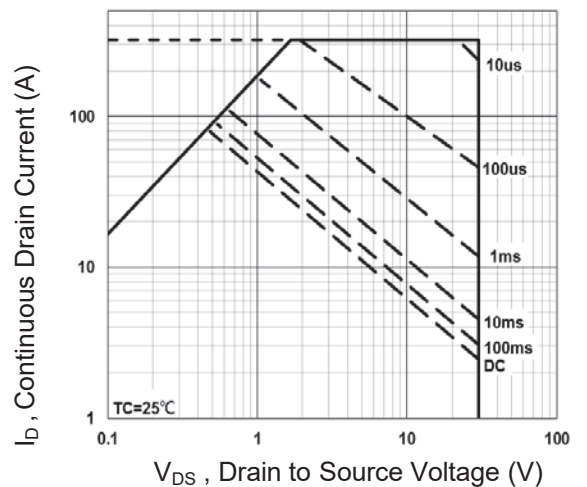
**Fig.3 Normalized  $V_{th}$  vs.  $T_j$**



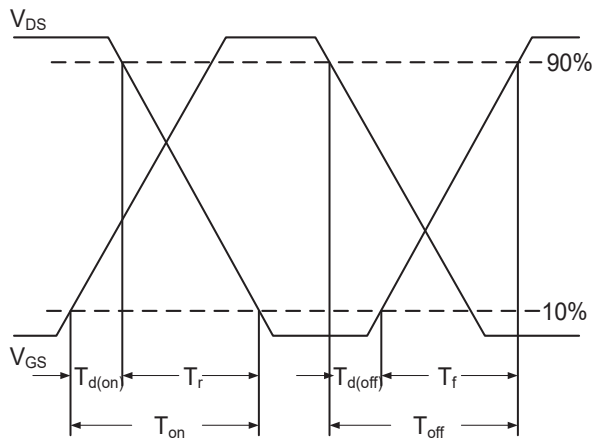
**Fig.4 Gate Charge Waveform**



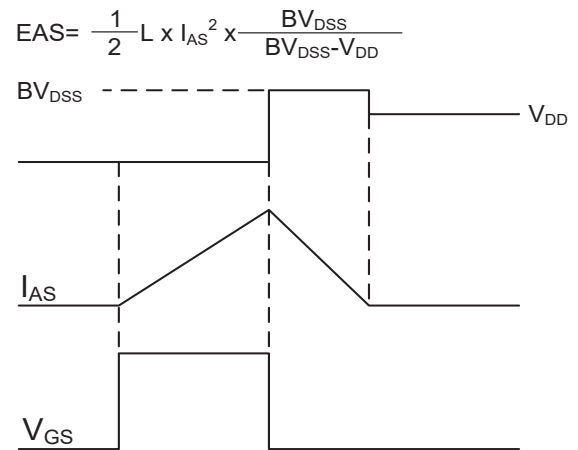
**Fig.5 Normalized Transient Impedance**



**Fig.6 Maximum Safe Operation Area**

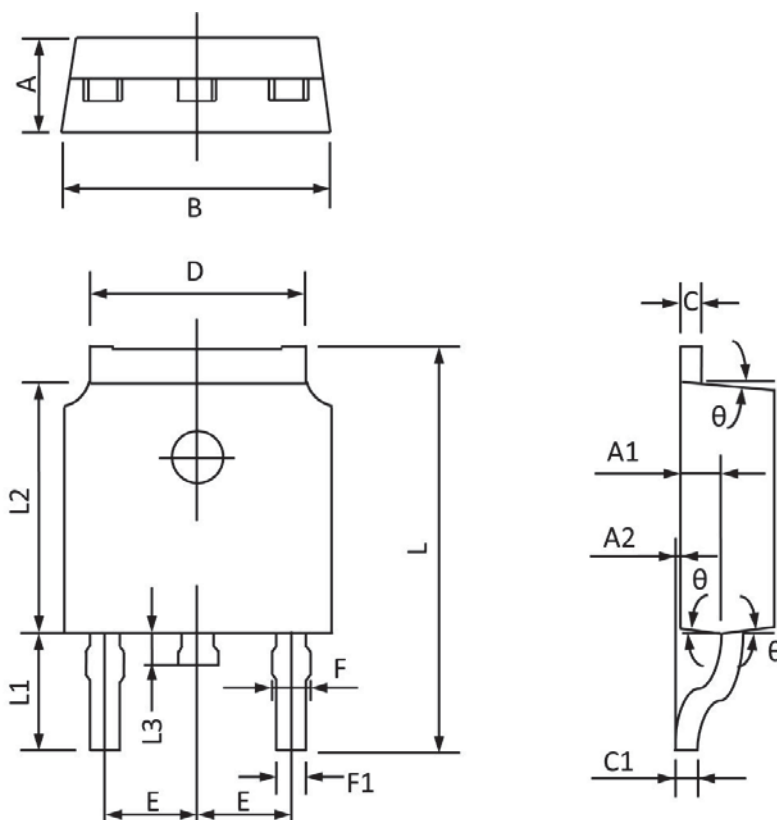


**Fig.7 Switching Time Waveform**



**Fig.8 EAS Waveform**

## TO-252 PACKAGE INFORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	2.20	2.40	0.087	0.094
A1	0.91	1.11	0.036	0.044
A2	0.00	0.15	0.000	0.006
B	6.50	6.70	0.256	0.264
C	0.46	0.580	0.018	0.230
C1	0.46	0.580	0.018	0.030
D	5.10	5.46	0.201	0.215
E	2.186	2.386	0.086	0.094
F	0.74	0.94	0.029	0.037
F1	0.660	0.860	0.026	0.034
L	9.80	10.40	0.386	0.409
L1	2.9REF		0.114REF	
L2	6.00	6.20	0.236	0.244
L3	0.60	1.00	0.024	0.039
$\theta$	3°	9°	3°	9°